

Application No.: 10/667,605**Docket No.: 4459-130****AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1-9. (canceled)
10. (currently amended) An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface and having an optical element;
a plurality of bonding pads disposed on the upper surface;
a plurality of bonding wires electrically connecting the chip to the bonding pads;
a window made of a transparent material mounted on the optical element of the chip for allowing light to transmit through the window and interact with the optical element; and
~~a transparent~~ an encapsulant formed on the substrate for fixing the window and encapsulating the chip and the bonding wires.
11. (previously presented) The optical semiconductor package as claimed in claim 10, wherein the encapsulant is formed by means of an overmolding process.
12. (original) The optical semiconductor package as claimed in claim 10, wherein the window further comprises a ledge for securing the window in the encapsulant.
13. (original) The optical semiconductor package as claimed in claim 10, wherein the encapsulant is made of an opaque material.

Application No.: 10/667,605**Docket No.: 4459-130**

14. (original) The optical semiconductor package as claimed in claim 10, wherein the window is a lens.

15. (original) The optical semiconductor package as claimed in claim 10, further comprising:

an adhesive for mounting the window on the optical element of the chip.

16. (withdrawn) A method for manufacturing an optical semiconductor package, comprising the following steps of:

providing a substrate;

mounting a chip having an optical element on the substrate;

bonding a plurality of bonding wires to the chip and the substrate for electrically connecting the chip to the substrate;

mounting a window on the optical element of the chip; and

forming an encapsulant on the substrate for fixing the window and encapsulating the chip and the bonding wires.

17-19. (canceled)

20. (currently amended) An optical semiconductor package, comprising:

a substrate having opposite upper and lower surfaces;

a chip disposed on the upper surface and having an optical element;

a plurality of bonding pads disposed on the upper surface;

a plurality of bonding wires electrically connecting the chip to the bonding pads ;

a window made of a transparent material for allowing light to transmit through the window and interact with the optical element;

a support supporting the window for positioning the window corresponding to the optical

Application No.: 10/667,605Docket No.: 4459-130

element of the chip; and

~~a transparent~~ an encapsulant formed on the substrate for hermetically fixing the support on the substrate.

21. (previously presented) The optical semiconductor package as claimed in claim 20, wherein the encapsulant is formed by means of an overmolding process.

22. (previously presented) The optical semiconductor package as claimed in claim 20, wherein the window is hermetically disposed on the support.

23. (original) The optical semiconductor package as claimed in claim 20, wherein the encapsulant is made of an opaque material.

24. (original) The optical semiconductor package as claimed in claim 20, wherein the window is a lens.

25. (canceled)

26. (previously presented) The optical semiconductor package as claimed in claim 10, wherein said optical element comprises one selected from the group consisting of an optical sensor and an imaging sensor.

27. (previously presented) The optical semiconductor package as claimed in claim 26, wherein

said window has opposite upper and lower surfaces and a side surface connecting the upper and lower surfaces of said window;

said package further comprises a transparent adhesive layer attaching the lower surface of

Application No.: 10/667,605**Docket No.: 4459-130**

said window to an upper surface of said optical element of said chip; and

said encapsulant surrounds said window and directly contacts the side surface of said windows, while leaving the upper surface of said windows exposed from an upper surface of said encapsulant.

28. (previously presented) The optical semiconductor package as claimed in claim 20, wherein said optical element is an optically sensitive element.

29. (previously presented) An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface of said substrate and having an optical sensor;
a plurality of bonding wires electrically connecting the chip to the substrate;
a supporting wall extending upwardly from the upper surface of said substrate;
a window made of a transparent material and supported by said supporting wall at a location above said optical sensor for allowing light to transmit through the window and interact with the optical sensor; and
an encapsulant formed on the upper surface of said substrate to surround said supporting wall.

30. (previously presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant includes
an outer portion covering an outer side surface of said supporting wall; and
an inner portion encapsulating said chip and said wires and covering an inner side surface of said supporting wall, wherein said inner portion of said encapsulant is transparent.

31. (previously presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant, said supporting wall, said window and said substrate together define a

Application No.: 10/667,605

Docket No.: 4459-130

hermetically sealed cavity in which said chip, said optical sensor and said wires are disposed.